

| / ELECTRONICS | Maxwell | HFSS | HFSS-IC | Siwave | Siwave Plus | Q3D Extractor | Icepak | Motor-CAD | EMC Plus | Charge Plus | Nuhertz FilterSolutions | SynMatrix Filter | SynMatrix Filter AI+ | Electronics AI+ | Electronics Pro | Electronics Enterprise |
|--|---------|------|---------|--------|-------------|---------------|--------|-----------|----------|-------------|-------------------------|------------------|----------------------|-----------------|-----------------|------------------------|
| LOW FREQUENCY ELECTROMAGNETICS | | | | | | | | | | | | | | | | |
| Electrostatics | ● | | | | | | | | | | | | | | ● | ● |
| AC Conduction | ● | | | | | | | | | | | | | | ● | ● |
| DC Conduction | ● | | | | | | | | | | | | | | ● | ● |
| Magnetostatics | ● | | | | | | | | | | | | | | ● | ● |
| Adaptive Field Mesh | ● | | | | | | | | | | | | | | ● | ● |
| AC Harmonic Magnetic | ● | | | | | | | | | | | | | | ● | ● |
| Electric Transient | ● | | | | | | | | | | | | | | | ● |
| MAGNETIC TRANSIENT | | | | | | | | | | | | | | | | |
| Translational Motion | ● | | | | | | | | | | | | | | ● | ● |
| Fully Automatic Symmetrical Mesh Generation | ● | | | | | | | | | | | | | | ● | ● |
| Rotational Motion | ● | | | | | | | | | | | | | | ● | ● |
| Non-Cylindrical Motion | ● | | | | | | | | | | | | | | ● | ● |
| Advanced Embedded Circuit Coupling | ● | | | | | | | | | | | | | | ● | ● |
| Circuit Coupling with Adaptive Time Stepping | ● | | | | | | | | | | | | | | ● | ● |
| Direct and Iterative Matrix Solvers | ● | | | | | | | | | | | | | | ● | ● |
| ADVANCED ELECTROMAGNETIC MODELING | | | | | | | | | | | | | | | | |
| Vector Hysteresis Modeling | ● | | | | | | | | | | | | | | ● | ● |
| Multi-Conductive Terminals Modelling (PCBs, Busbars etc.) / A-Phi Solver | ● | | | | | | | | | | | | | | | ● |
| 3D Layout Component Integration (ECAD) for LF Electronics Design | ● | | | | | | | | | | | | | | | |
| Hysteresis Modeling for Anisotropic Material | ● | | | | | | | | | | | | | | ● | ● |
| Frequency Dependent Reduced Order Models | ● | | | | | | | | | | | | | | ● | ● |
| Reduced Order Model Extraction (Linear-Motion, Rotational-Motion, No-Motion) | ● | | | | | | | | | | | | | | ● | ● |
| Functional Magnetization Direction | ● | | | | | | | | | | | | | | ● | ● |
| Magnetization/De- Magnetization Modeling | ● | | | | | | | | | | | | | | ● | ● |
| Manufacturing Dependent Core L Loss Models | ● | | | | | | | | | | | | | | ● | ● |
| Noise – Vibration Modeling | ■ | | | | | | | | | | | | | | ■ | ■ |
| Temperature Dependent De-Magnetization Modeling | ● | | | | | | | | | | | | | | ● | ● |

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|--|---------|------|---------|--------|-------------|---------------|--------|-----------|----------|-------------|-------------------------|------------------|----------------------|-----------------|-----------------|------------------------|
| ADVANCED ELECTROMAGNETIC MODELING | | | | | | | | | | | | | | | | |
| Temperature Dependent Core Loss Computation | ● | | | | | | | | | ● | ● | | | | ● | ● |
| Lamination Modeling | ● | | | | | | | | | ● | ● | | | | ● | ● |
| Magnetostriction and Magnetoelastic Modeling | ● | | | | | | | | | ● | ● | | | | ● | ● |
| Hardware in the Loop Modeling | ● | | | | | | | | | ● | ● | | | | ● | ● |
| Integrated Motor Synthesis and Design Kit | ● | | | | | | | | | ● | ● | | | | ● | ● |
| Integrated Planar Magnetics Synthesis and Design Kit | ● | | | | | | | | | ● | ● | | | | ● | ● |
| Temperature Dependent Litz Wire Modeling | ● | | | | | | | | | ● | ● | | | | ● | ● |
| Litz Wire Modeling | ● | | | | | | | | | ● | ● | | | | ● | ● |
| DESIGN SOLUTION FOR ELECTRICAL MACHINE | | | | | | | | | | | | | | | | |
| Template-Based Magnetic Topologies | | | | | | | | ● | | | | | | | | |
| Template-Based Cooling Topologies | | | | | | | | ● | | | | | | | | |
| Adaptive Template-Based Topologies | | | | | | | | ● | | | | | | | | |
| Magnetic 2D FEA with Analytical Solution | | | | | | | | ● | | | | | | | | |
| Thermal 2D FEA | | | | | | | | ● | | | | | | | | |
| 3D Thermal and Fluid Network | | | | | | | | ● | | | | | | | | |
| Optimization Workflow | | | | | | | | ■ | | | | | | | | |
| Temperature Dependent Duty-Cycle Analysis | | | | | | | | ● | | | | | | | | |
| Manufacturing Effects Due to Winding Impregnation and Housing Interfaces | | | | | | | | ● | | | | | | | | |
| Linear Structural 2D FEA | | | | | | | | ● | | | | | | | | |
| Noise Vibration Harness Analytical Modelling | | | | | | | | ● | | | | | | | | |
| Electrothermal Reduced Order Model (FMU) | | | | | | | | ● | | | | | | | | |
| HIGH FREQUENCY ELECTROMAGNETICS | | | | | | | | | | | | | | | | |
| Fully Automated Adaptive Mesh Refinement | | ● | | | | | | | | | ● | | | | | |
| Multi-Frequency Broadband Adaptive Meshing | | ● | | | | | | | | | ● | | | | | |
| Frequency Domain Finite Element (FEM) Analysis | | ● | | | | | | | | | ● | | | | | |
| Frequency Domain Integral Equation (MoM) Analysis | | ● | | | | | | | | | ● | | | | | |
| Time Domain FEM Analysis | | ● | | | | | | | | | ● | | | | | |
| FEM Eigenmode Analysis | | ● | | | | | | | | | ● | | | | | |
| MoM Characteristic Mode Analysis | | ● | | | | | | | | | ● | | | | | |
| Physical Optics (PO) Analysis | | ● | ● | | | | | | | | | | | | | ● |

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|---|---------|------|---------|--------|-------------|---------------|--------|-----------|----------|-------------|-------------------------|------------------|----------------------|-----------------|-----------------|------------------------|
| HIGH FREQUENCY ELECTROMAGNETICS | | | | | | | | | | | | | | | | |
| Shooting and Bouncing Ray+ (SBR+) Analysis | | ● | ● | | | | | | | | | | | | | ● |
| Physical Theory of Diffraction (PTD) Correction for SBR | | ● | ● | | | | | | | | | | | | | ● |
| Uniform Theory of Diffraction (UTD) Correction for SBR | | ● | ● | | | | | | | | | | | | | ● |
| Visual Ray Tracing for SBR+ Analysis | | ● | ● | | | | | | | | | | | | | ● |
| SBR+ Creeping Wave Correction for RCS of Curved Objects | | ● | ● | | | | | | | | | | | | | ● |
| Range Doppler Plots for Radar Scenario Analyses | | | | | | | | | | | | | | | | ● |
| Accelerated Doppler Processing (ADP) for SBR+ Range Doppler | | | | | | | | | | | | | | | | ● |
| RF Filter Synthesis and Design - Planar | | | | | | | | | | | ● | ● | | | | |
| Digital Filter Synthesis and Design | | | | | | | | | | | ● | | | | | |
| RF Filter Synthesis and Design - Cavity, Coaxial, SiW | | | | | | | | | | | | ● | | | | |
| RF Filter Optimization | | | | | | | | | | | | ● | | | | |
| RF Filter AI Driven Optimization | | | | | | | | | | | | | ● | ● | | |
| Domain Decomposition Method (DDM) for Frequency Domain | | ● | ● | | | | | | | | | | | | | ● |
| FEM Analysis | | ● | ● | | | | | | | | | | | | | ● |
| Hybrid Finite Element/ Integral Equation Analysis | | ● | ● | | | | | | | | | | | | | ● |
| Efficient Wirebond Package Meshing | | ● | ● | | | | | | | | | | | | | ● |
| UI Coupled Finite Element and/or IE with SBR+ Analysis | | ● | ● | | | | | | | | | | | | | ● |
| Modal Wave Port Excitation | | ● | ● | | | | | | | | | | | | | ● |
| Terminal Wave Port Excitations | | ● | ● | | | | | | | | | | | | | ● |
| Lumped, Voltage and Current Excitations | | ● | ● | | | | | | | | | | | | | ● |
| Circuit Port Excitations | | ● | ● | | | | | | | | | | | | | ● |
| Parametric Antenna Excitations for SBR+ | | ● | ● | | | | | | | | | | | | | ● |
| Floquet Excitations | | ● | ● | | | | | | | | | | | | | ● |
| Incident Wave Excitation | | ● | ● | | | | | | | | | | | | | ● |
| Magnetic Ferrite Bias Excitation | | ● | ● | | | | | | | | | | | | | ● |
| Perfect Electric and Magnetic Boundary | | ● | ● | | | | | | | | | | | | | ● |
| Finite Conductivity Boundary | | ● | ● | | | | | | | | | | | | | ● |
| Lumped RLC Boundary | | ● | ● | | | | | | | | | | | | | ● |
| Symmetry Boundary | | ● | ● | | | | | | | | | | | | | ● |

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|--|----------------|-------------|----------------|---------------|--------------------|----------------------|---------------|------------------|-----------------|--------------------|--------------------------------|-------------------------|-----------------------------|------------------------|------------------------|-------------------------------|
| HIGH FREQUENCY ELECTROMAGNETICS | | | | | | | | | | | | | | | | |
| Periodic Boundary | | ● | ● | | | | | | | | | | | | | ● |
| Frequency Dependent Materials | | ● | ● | | | | | | | | | | | | | ● |
| Spatial XYZ Material Properties Via Dataset | | ● | ● | | | | | | | | | | | | | ● |
| Higher and Mixed Order Elements | | ● | ● | | | | | | | | | | | | | ● |
| Curvilinear Element Mesh Correction | | ● | ● | | | | | | | | | | | | | ● |
| S,Y,Z Matrix Results | | ● | ● | | | | | | | | | | | | | ● |
| E, H, J, P Field Results | | ● | ● | | | | | | | | | | | | | ● |
| Direct and Iterative Matrix Solvers | | ● | ● | | | | | | | | | | | | | ● |
| Antenna Parameter Calculation | | ● | ● | | | | | | | | | | | | | ● |
| Infinite and Finite Antenna Array Calculations | | ● | ● | | | | | | | | | | | | | ● |
| Radar Cross Section Calculation | | ● | ● | | | | | | | | | | | | | ● |
| FSS, EBG and Metamaterial Calculation | | ● | ● | | | | | | | | | | | | | ● |
| Specific Absorption Rate Calculation | | ● | ● | | | | | | | | | | | | | ● |
| EMI/EMC Calculation | | ● | ● | | | | | | | | | | | | | ● |
| System Level EMI and RFI Analysis | | ● | ● | | | | | | | | | | | | ● | ● |
| Linear Circuit Analysis with EM Dynamic link | | ● | ● | | | | | | | | | | | | | ● |
| Integrated Antenna Synthesis and Design Kit | | ● | ● | | | | | | | | | | | | | ● |
| 5G SAR Standards Toolkit | | ● | ● | | | | | | | | | | | | | ● |
| Power Density and CDF | | ● | ● | | | | | | | | | | | | | ● |
| Radar Prep/Post Simulation Wizards | | ● | ● | | | | | | | | | | | | | ● |
| 3D Component Libraries with User Controlled Parametrics | | ● | ● | | | | | | | | | | | | | ● |
| 3D Component with Encryption Creation | | ● | ● | | | | | | | | | | | | | ● |
| 3D Component with Encryption Utilization | | ● | ● | | | | | | | | | | | | | ● |
| RF Discharge Solver | | ● | ● | | | | | | | | | | | | | ● |
| Mutli-paction Solver | | ● | ● | | | | | | | | | | | | | ● |
| Volumetric SBR+ for 3D Dielectrics | | ● | ● | | | | | | | | | | | | | ● |
| Surface Roughness Model for SBR+ | | ● | ● | | | | | | | | | | | | | ● |
| Accelerated Doppler Processing (ADP) for SBR+ Range-Doppler Analysis | | ● | ● | | | | | | | | | | | | | ● |

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|---|---------|------|---------|--------|-------------|---------------|--------|-----------|----------|-------------|-------------------------|------------------|----------------------|-----------------|-----------------|------------------------|
| POWER AND SIGNAL INTEGRITY BOARD SIMULATION CAPABILITIES | | | | | | | | | | | | | | | | |
| Electronics Desktop 3D Layout GUI | | ● | ● | ● | ● | ● | ● | | | | | | | | | ● |
| ECAD Translation (Altium, Cadence, Mentor, Pulsonix, & Zuken) | ● | ● | ● | ● | ● | | ● | | | | | | | | | ● |
| MCAD (.x_b) Generation from ECAD | | ● | ● | ● | ● | | | | ● | ● | | | | | | ● |
| Lead Frame Editor | | ● | ● | ● | ● | | | | | | | | | | | ● |
| DC Voltage, Current and Power Analysis for PKG/PCB | | | | ● | ● | | | | | | | | | | | ● |
| DC and AC Joule Heating with Ansys Icepak | | | | ■ | ■ | | ■ | | | | | | | | | ● |
| Passive Excitation Plane Resonance Analysis | | | | ● | ● | | | | | | | | | | | ● |
| Driven Excitation Plane Resonance Analysis | | | | ● | ● | | | | | | | | | | | ● |
| Automated Decoupling Analysis | | | | ● | ● | | | | | | | | | | | ● |
| Capacitor Loop Inductance Analysis | | | | ● | ● | | | | | | | | | | | ● |
| AC SYZ Analysis | | | | ● | ● | | | | | | | | | | | ● |
| Dynamically Linked Electromagnetic Field Solvers | | ● | ● | ● | ● | | | | | | | | | | | ● |
| Chip, Package, PCB Analysis (CPM) | | ● | ● | ● | ● | | | | | | | | | | | ● |
| Near-Field EMI Analysis | | ● | ● | | ● | | | | | | | | | | | ● |
| Far-Field EMI Analysis | | ● | ● | | ● | | | | | | | | | | | ● |
| EMI/EMC Full Board Scan | | | | | ● | | | | | | | | | | | ● |
| Characteristic Impedance (Zo) L PKG/PCB Scan | | | | | ● | | | | | | | | | | | ● |
| Full PCB/PKG Cross-Talk Scanning | | | | | ● | | | | | | | | | | | ● |
| TDR Wizard | | | | | ● | | | | | | | | | | | ● |
| TDR Analysis | | ● | ● | ● | ● | | | | | | | | | | ● | ● |
| Transient IBIS Circuit Analysis | | ● | ● | ● | ● | | | | | | | | | | ● | ● |
| Signal Net Analyzer | | | | | ● | | | | | | | | | | | ● |
| SerDes IBIS-AMI Circuit Analysis | | | ● | | ● | | | | | | | | | | | ● |
| Macro-Modeling (Network Data Explorer) | ● | ● | ● | ● | ● | | | | | | | | | | | ● |
| Steady State AC (LNA) Analysis | | ● | ● | ● | ● | | | | | | | | | | | ● |

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| POWER AND SIGNAL INTEGRITY BOARD SIMULATION CAPABILITIES | | | | | | | | | | | | | | | | |
| SPISIM Com and USB-C Compliance | | | ● | | | | | | | | | | | | | ● |
| SPISIM IBIS AMI Generation | | | ● | | | | | | | | | | | | | ● |
| Synopsys HSPICE Integration | | ● | ● | ● | | | | | | | | | | | | ● |
| Cadence PSPICE Support | | ● | ● | ● | | | | | | | | | | | | ● |
| Electromagnetically Circuit Driven Field Solvers | | ● | ● | ● | | ● | | | | | | | | | | ● |
| RLCG PARASITIC EXTRACTION | | | | | | | | | | | | | | | | |
| DCRL, ACRL & CG Solver | | | ● | | | ● | ● | | | ● | | | | | ● | ● |
| IC Packaging RLCG IBIS Extraction for Signals & Power | | | ● | | | ● | ● | | | | | | | | | ● |
| Touchpanel RLCG Unit Cell Extraction | | | ● | | | ● | ● | | | | | | | | | ● |
| Adaptive Meshing for Accurate Extraction | | | ● | | | ● | ● | | | ● | | | | | ● | ● |
| Bus Bar RLCG Extraction | ● | ● | ● | | | ● | ● | | | ● | | | | | ● | ● |
| Power Inverter & Converter Component Extraction | | | ● | | | ● | ● | | | | | | | | | ● |
| 3D Component Library | | | ● | | | ● | ● | | | | | | | | | ● |
| Reduced RLCG Matrix Operations | | | ● | | | ● | ● | | | | | | | | | ● |
| SPICE Equivalent Modeling Export | | | ● | | | ● | ● | | | ● | | | | | | ● |
| DCRL & ACRL Joule Heating Analysis with Icepak | | | ● | | | ● | ● | | | | | | | | ● | ● |
| Macro-Modeling (Network Data Explorer) | | | ● | | | ● | ● | | | | | | | | | ● |
| 2D Cable Modeling Toolkit | | | ● | | | ● | ● | | | | | | | | | ● |
| ELECTRONICS COOLING | | | | | | | | | | | | | | | | |
| Multi-Mode Heat Transfer | | ■ | ■ | ■ | ■ | ■ | ● | | | | | | | | | ● |
| Steady-State and Transient | | | | | | | ● | | | | | | | | | ● |
| CFD Analysis | | | | | | | ● | | | | | | | | | ● |
| Turbulent Heat Transfer | | | | | | | ● | | | | | | | | | ● |
| Multiple-Fluid Analysis | | | | | | | ● | | | | | | | | | ● |
| Species Transport | | | | | | | ● | | | | | | | | | ● |
| Solar Loading | | | | | | | ● | | | | | | | | | ● |
| Reduced Order Flow and Thermal | | | | | | | ● | | | | | | | | | ● |

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|--|---------|------|---------|--------|-------------|---------------|--------|-----------|----------|-------------|-------------------------|------------------|----------------------|-----------------|-----------------|------------------------|
| ELECTRONICS COOLING | | | | | | | | | | | | | | | | |
| Network Modeling | | | | | | | ● | | | | | | | | | ● |
| Joule Heating Analysis | | | | | | | ● | | | | | | | | | ● |
| Thermo-Electric Cooler Modeling | | | | | | | ● | | | | | | | | | ● |
| Thermostat Modeling | | | | | | | ● | | | | | | | | | ● |
| Package Characterization | | | | | | | ● | | | | | | | | | ● |
| CABLE MODELING | | | | | | | | | | | | | | | | |
| Finite Difference Time Domain Analysis | | | | | | | | | ● | | | | | | | |
| Multi-Conductor Transmission Line Analysis | ● | ● | ● | ● | ● | ● | ● | | ● | | | | | | ● | ● |
| Two-Way Coupling FDTD and Transmission Line Solver | | | | | | | ● | | ● | | | | | | | ▲ |
| Twisted Conductors | | | | | | | ● | | ● | | | | | | | |
| Seam Impedance | | | | | | | ● | | ● | | | | | | | |
| Cable Junctions | | | | | | | ● | | ● | | | | | | | |
| Braided Shield Support | | ▲ | ▲ | | | | ● | | ● | | | | | | | |
| Pin Voltage, Current Density, Plane Wave Excitations | | | | | | | ● | | ● | | | | | | | |
| Multi-Conductor and Multi-Shield Support | | | | | | | ● | | ● | | | | | | | ● |
| Uses Discovery Modeler UI | | | | | | | ● | | ● | | | | | | | |
| Thin Surface and Thin Wire Algorithms | | | | | | | ● | | ● | | | | | | | |
| HPC FOR ELECTRONICS | | | | | | | | | | | | | | | | |
| GPU Support | ● | ● | ● | | | | ● | | | | | | | | ● | ● |
| HPC Meshing, Multi-Domain, Multi-Technology | | ● | ● | ● | ● | ● | | | | | | | | | ● | ● |
| HPC Accelerated Frequency Sweeps | ● | ● | ● | | | | | | | | | | | | ● | ● |
| HPC Accelerated Broadband Fast Frequency Sweep | | ● | ● | | | | | | | | | | | | ● | ● |
| HPC Distributed Hybrid Solving | | ● | ● | | | | | | | | | | | | ● | ● |
| HPC Enabled Domain Decomposition Method | ● | ● | ● | | | | | | | | | | | | ● | ● |
| HPC Time Decomposition Method | ● | | | | | | | | | | | | | | ● | ● |
| HPC Enabled Multi-port Excitation Acceleration | | ● | ● | | | | | | | | | | | | ● | ● |
| HPC Acceleration for DCRL, ACRL and CG | | | | | | ● | | | | | | | | | ● | ● |
| HPC 2D Skew Parallel Processing | ● | | | | | | | | | | | | | | ● | ● |
| HPC Enabled Parallel Processing | ● | ● | ● | | | | ● | | | | | | | | ● | ● |

● Full Support ▲ Limited Capability ■ Requires more than 1 product

| / ELECTRONICS | Maxwell | HFSS | HFSS-IC | Siwave | Siwave Plus | Q3D Extractor | Icepak | Motor-CAD | EMC Plus | Charge Plus | Nuhertz FilterSolutions | SynMatrix Filter | SynMatrix Filter AI+ | Electronics AI+ | Electronics Pro | Electronics Enterprise | |
|--|---------|------|---------|--------|-------------|---------------|--------|-----------|----------|-------------|-------------------------|------------------|----------------------|-----------------|-----------------|------------------------|---|
| SYSTEM MODELING FOR POWER ELECTRONICS | | | | | | | | | | | | | | | | | |
| Circuit Simulation | ● | ● | ● | ● | ● | ● | ● | | | | | | | | ● | ● | |
| Block Diagram Simulation | ● | ● | ● | ● | ● | ● | ● | | | | | | | | ● | ● | |
| State Machine Simulation | ● | ● | ● | ● | ● | ● | ● | | | | | | | | ● | ● | |
| VHDL-AMS Simulation | ● | ● | ● | ● | ● | ● | ● | | | | | | | | ● | ● | |
| Integrated Graphical Modeling Environment | ● | ● | ● | ● | ● | ● | ● | | | | | | | | ● | ● | |
| Power Electronics Component Libraries | ● | ● | ● | ● | ● | ● | ● | | | | | | | | ● | ● | |
| Reduced Order Modeling | ● | ● | ● | ● | ● | ● | ● | | | | | | | | ● | ● | |
| Power Electronic Device and Module Characterization | ● | ● | ● | ● | ● | ● | ● | | | | | | | | ● | ● | |
| Push-Back Excitation | ● | ● | ● | ● | ● | ● | | | | | | | | | ● | ● | |
| Co-Simulation with Low Frequency Electromagnetics | ● | | | | | | | | | | | | | | ● | ● | |
| Co-Simulation with MathWorks Simulink | ● | ● | ● | ● | ● | ● | ● | | | | | | | | ● | ● | |
| IC CAPABILITIES | | | | | | | | | | | | | | | | | |
| Solve projects with encrypted tech files | | ● | ● | | | ● | | | | | | | | | | | ● |
| RaptorX solver | | | ● | | | | | | | | | | | | | | |
| LDE - Layout Dependent Effects | | | ● | | | | | | | | | | | | | | |
| AI / ML CAPABILITIES | | | | | | | | | | | | | | | | | |
| Siwave simulation runtime and memory prediction | | | | | | | | | | | | | | ● | | | |
| SynMatrix AI optimization | | | | | | | | | | | | | | ● | | | |
| SYSTEM MODELING FOR RF / MICROWAVE | | | | | | | | | | | | | | | | | |
| Radio Frequency Interference (RFI) System Solver | | ● | ● | | | | | | | | | | | | ● | ● | |
| Electromagnetic Interference System Solver | | ● | ● | | | | | | | | | | | | ● | ● | |
| RF Link Budget Analysis | | ● | ● | | | | | | | | | | | | ● | ● | |
| RF Co-Site and Antenna Coexistence Analysis | | ● | ● | | | | | | | | | | | | ● | ● | |
| Automated Diagnostics for Rapid Root-Cause Analysis | | ● | ● | | | | | | | | | | | | ● | ● | |
| RF Component Library | | ● | ● | | | | | | | | | | | | ● | ● | |
| SYSTEM MODELING FOR SI / PI | | | | | | | | | | | | | | | | | |
| SerDes Channel Modeling - IBIS-AMI, QuickEye and VerifEye | | | ● | | ● | | | | | | | | | | | | ● |
| Multi-Drop & Parallel Bus Modeling - IBIS, HSPICE, Spectre, PSPICE, and Nexxim Transient | | ● | ● | ● | ● | | | | | | | | | | | | ● |

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| / ELECTRONICS | Maxwell | HFSS | HFSS-IC | Siwave | Siwave Plus | Q3D Extractor | Icepak | Motor-CAD | EMC Plus | Charge Plus | Nuhertz FilterSolutions | SynMatrix Filter | SynMatrix Filter AI+ | Electronics AI+ | Electronics Pro | Electronics Enterprise |
|---|---------|------|---------|--------|-------------|---------------|--------|-----------|----------|-------------|-------------------------|------------------|----------------------|-----------------|-----------------|------------------------|
| SYSTEM MODELING FOR SI / PI | | | | | | | | | | | | | | | | |
| Network Data Exploration | ● | ● | ● | ● | ● | | | | | | | | | | | ● |
| TDR analysis | | ● | ● | ● | ● | | | | | | | | | | | ● |
| Steady State AC (LNA) Analysis | | ● | ● | ● | ● | | | | | | | | | | | ● |
| MULTIPHYSICS-PLATFORM TECHNOLOGIES | | | | | | | | | | | | | | | | |
| Advanced, Automated Data Exchange | ● | ● | ● | ● | ● | ● | ● | | | | | | | | ● | ● |
| Drag-n-Drop Multiphysics | ■ | ■ | ■ | ■ | ■ | ■ | ■ | | | | | | | | ■ | ● |
| Direct Coupling Between Physics | ● | ● | ● | ● | ● | ● | ● | | | | | | | | ● | ● |
| Collaborative Workflows | ● | ● | ● | ● | ● | ● | ● | | | | | | | | ● | ● |
| Fully Managed Co-Simulation | ● | ● | ● | ● | ● | ● | ● | | | | | | | | ● | ● |
| Flexible Solver Coupling Options | ● | ● | ● | ● | ● | ● | ● | | | | | | | | ● | ● |
| MULTIPHYSICS ELECTRO-THERMAL INTERACTION | | | | | | | | | | | | | | | | |
| Convection Cooled Electronics | ■ | ■ | ■ | ■ | ■ | ■ | ■ | | | | | | | | | ● |
| Conduction Cooled Electronics | ■ | ■ | ■ | ■ | ■ | ■ | ■ | | | | | | | | | ● |
| High Frequency Thermal Management | | ■ | ■ | | | | ■ | | | | | | | | | ● |
| Low Frequency Thermal Management | ■ | | | | | | ■ | | | | | | | | | ● |
| MATERIALS FOR ELECTRONICS | | | | | | | | | | | | | | | | |
| Granta Materials Data for Simulation | ■ | ■ | ■ | ■ | ■ | ■ | ■ | ■ | | | | | | | ■ | ■ |
| Granta MI Materials Gateway | ■ | ■ | ■ | ■ | ■ | ■ | ■ | ■ | | | | | | | ■ | |
| Ansys Granta Advanced Materials – Electromagnetic | ■ | ■ | ■ | ■ | ■ | ■ | ■ | ▲ | | | | | | | | ■ |
| MISCELLANEOUS | | | | | | | | | | | | | | | | |
| Integrated Windows HPC Support | ● | ● | ● | ● | ● | ● | ● | | | | | | | | | |
| Integrated IBM Spectrum LSF Support | ● | ● | ● | ● | ● | ● | ● | | | | | | | | | |
| Customizable 3rd Party Scheduler Support | ● | ● | ● | ● | ● | ● | ● | | | | | | | | | |
| Support ACT Extensions | ▲ | ▲ | ▲ | | | ▲ | ▲ | | | | | | | | | ▲ |
| Parallel Solving with Ansys Cloud Launched from Desktop | ● | ● | ● | ● | ● | ● | ● | | | | | | | | | |
| Elastic Licensing | ● | ● | ● | ● | ● | ● | ● | ● | | | | | | | | |
| CHARGING AND DISCHARGING MODELING | | | | | | | | | | | | | | | | |
| Internal Charging | | | | | | | | | | ● | | | | | | |
| Electrostatic Discharge in Air | | | | | | | | | | ● | | | | | | |
| Surface Charging | | | | | | | | | | ● | | | | | | |
| 3D Particle Transport | | | | | | | | | | ● | | | | | | |
| Arcing in Solid Dielectrics | | | | | | | | | | ● | | | | | | |
| Coupled Charging Simulations | | | | | | | | | | ● | | | | | | |
| CERTIFICATION AND COMPLIANCE | | | | | | | | | | | | | | | | |
| ISO 26262 | ● | ● | | | | ● | | | | | | | | | ● | |

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